

WHAT IS CLAIMED IS:

1. A socket for a semiconductor device, comprising:
 - 5 a socket body having a semiconductor device placement section for selectively accommodating one of a plurality of semiconductor devices having contour dimensions different from each other, to be electrically connected to contact terminals;
 - 10 a pressing member having an touch portion brought in contact with said semiconductor device and pressing said semiconductor device toward said contact terminals, said pressing member being driven by a pressing member driving mechanism in accordance with
 - 15 the attachment or detachment of said semiconductor device relative to said semiconductor device placement section, for holding said semiconductor device in said semiconductor device placement section; and
- 20 wherein, when said pressing member driving mechanism moves said touch portion of said pressing member to be away from said semiconductor device to a position in readiness at which said touch portion of said pressing member is not interfered with said semiconductor device upon the attachment or detachment
- 25 of said semiconductor device, a portion of said pressing member is bulged outwardly from an end of said socket body via an opening of said socket body.

2. A socket for a semiconductor device,
comprising:

- a socket body having a semiconductor device
- 5 placement section for selectively accommodating one of a plurality of semiconductor devices having contour dimensions different from each other, to be electrically connected to contact terminals;
- a pressing member having an touch portion brought in contact with said semiconductor device and pressing said semiconductor device toward said contact terminals, for holding said semiconductor device in said semiconductor device placement section; and
- 15 a cover member supported by said socket body in a movable manner for bring said touch portion of said pressing member into contact with or away from said semiconductor device in accordance with the attachment or detachment of said semiconductor device relative to said semiconductor device placement section;
- 20 wherein, said cover member and said socket body have openings, respectively, so that when said cover member causes said touch portion of said pressing member to be away from said semiconductor device to a position in readiness at which said touch portion of said pressing member is not interfered with said semiconductor device, a portion of said pressing member is bulged outwardly from an end of said socket

body via the openings.

3. A socket for a semiconductor device as claimed in claim 1, wherein said socket comprising:

5 a first pressing member for holding said semiconductor device in said semiconductor device placement section, having a proximal end supported in a moveably rotationally manner at one end of said socket body and an touch portion formed at the 10 proximal end while being deviated in one widthwise direction to be in contact with said semiconductor device so that said semiconductor device is pressed toward said contact terminals; and

15 a second pressing member for holding said semiconductor device in said semiconductor device placement section in association with said first pressing member, having a proximal end supported in a moveably rotationally manner at the other end of said socket body and an touch portion formed at the 20 proximal end corresponding to said touch portion of said first pressing member while being deviated in said other widthwise direction to be in contact with said semiconductor device so that the semiconductor device is pressed toward said contact terminals.

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4. A socket for a semiconductor device as claimed in claim 1, wherein said socket comprising:

5 a first pressing member for holding said semiconductor device in said semiconductor device placement section, having a proximal end supported in a moveably rotationally manner at one end of said socket body and an touch portion in contact with said semiconductor device and pressing said semiconductor device toward said contact terminals; and

10 a second pressing member for holding said semiconductor device in said semiconductor device placement section in association with said first pressing member, having a proximal end supported in a moveably rotationally manner at the other end of said socket body and an touch portion in contact with said semiconductor device so that said semiconductor device
15 is pressed toward said contact terminals; wherein
 said second pressing member has a recess for allowing a portion of said first pressing member to enter.

20 5. A socket for a semiconductor device as claimed in claim 2, wherein said socket comprising:

25 a first pressing member for holding said semiconductor device in said semiconductor device placement section, having a proximal end supported in a moveably rotationally manner at one end of said socket body and an touch portion formed at the proximal end while being deviated in one widthwise

direction to be in contact with said semiconductor device so that said semiconductor device is pressed toward said contact terminals; and

5 a second pressing member for holding said semiconductor device in said semiconductor device placement section in association with said first pressing member, having a proximal end supported in a moveably rotationally manner at the other end of said socket body and an touch portion formed at the proximal end corresponding to said touch portion of said first pressing member while being deviated in said other widthwise direction to be in contact with said semiconductor device so that the semiconductor device is pressed toward said contact terminals.

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6. A socket for a semiconductor device as claimed in claim 2, wherein said socket comprising:

20 a first pressing member for holding said semiconductor device in said semiconductor device placement section, having a proximal end supported in a moveably rotationally manner at one end of said socket body and an touch portion in contact with said semiconductor device and pressing said semiconductor device toward said contact terminals; and

25 a second pressing member for holding said semiconductor device in said semiconductor device placement section in association with said first

pressing member, having a proximal end supported in a moveably rotationally manner at the other end of said socket body and an touch portion in contact with said semiconductor device so that said semiconductor device
5 is pressed toward said contact terminals; wherein
said second pressing member has a recess for allowing a portion of said first pressing member to enter.

10 7. A socket for a semiconductor device comprising:

 a socket body having a semiconductor device placement section for placing said semiconductor device;

15 contact terminals, each having a contact portion movable to be close to or away from said semiconductor device placement section, for electrically connecting terminals of said semiconductor device to a signal input/output section via said contact portions; and

20 a cover member disposed in said socket body in a movable manner for causing the contact portions of said contact terminals to be close to or away from said semiconductor device placement section; wherein
when said cover member moves close to said socket

25 body, the contact portions of said contact terminals are away from said semiconductor device placement section and tip ends of engagement end sections of

5 said contact terminals engaged with said cover member
are projected outwardly through an opening of said
cover member.

10 8. A socket for a semiconductor device as claimed
in claim 7, wherein when said cover member is made to
move close to said socket body, the tip end of the
engagement end section of said contact terminal is
made to move rotationally about a predetermined rotary
center positioned inside said socket body.

15 9. A socket for a semiconductor device as claimed
in claim 7, wherein position of the tip ends of the
engagement end sections of said contact terminals
disposed on a opposite sides of said semiconductor
device placement section between the both are
different in height each other.

20 10. A socket for a semiconductor device
comprising:

 a socket body having a semiconductor device
placement section for placing said semiconductor
device,

25 contact terminals, each having a contact portion
movable to be close to or away from said semiconductor
device placement section, for electrically connecting
terminals of said semiconductor device to a signal

input/output section via said contact portions, and
a lever member disposed in said socket body in a
moveably rotational manner for causing the contact
portions of said contact terminals to be close to or
5 away from said semiconductor device placement section,
and
a cover member disposed in said socket body in a
movable manner for moving rotationally said lever
member, wherein
10 when said cover member is made to move close to
said socket body, the contact portion of said contact
terminal is away from said semiconductor device
placement section and one end of said lever member
engaged with said cover member is projected outwardly
15 through an opening of said cover member.

11. A socket for a semiconductor device as
claimed in claim 10, wherein the inner peripheral
surfaces of said cover members for guiding one ends of
20 said lever members disposed on a opposite sides of
said semiconductor device placement section have
inclinations different from each other, respectively,
and a positions at which an end of the inner
peripheral surface of said cover member intersects the
25 outer peripheral surface of said cover member is
different in height in correspondence to the opposite
lever members each other.